Substitute for form 1449A/B/PTO				Complete if Known		
000#1110#	5 101 101111 1440F41	J.1. 1. O		Application Number	Not Yet Assigned	
INFO	ORMATIC	ON DISC	LOSURE	Filing Date	Concurrently Herewith	
STATEMENT BY APPLICANT			PLICANT	First Named Inventor	Masud Beroz	
				Art Unit	3729	
	(Use as man	y sheets as nec	essary)	Examiner Name	M. Trinh	
Sheet	1	of	2	Attorney Docket Number	TESSERA 3.0-205 A DIV	

			U.S. PA	TENT DOCUMENTS	
Examiner	Cite	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
Initials'	No.1	Number-Kind Code ² (if known)	MM-DO-1111		
100	AA	US-5,133,495	07/1992	ANGULAS ET AL.	
	AB	US-5,148,265	09-15-1992	KHANDROS ET AL.	
	AC	US-5,148,266	09-15-1992	KHANDROS ET AL.	
	AD	US-5,203,076	04/1993	BANERJI ET AL.	
	AE	US-5,232532	08/1993	HORI	
	AF	US-5,346,861	09-13-1994	KHANDROS ET AL.	
\neg	ĀĠ	US-5,431,328	07/1995	CHANG ET AL.	
	AH	US-5,518,964	05-21-1996	DISTEFANO ET AL.	
	Al	US-5,578,527	11/1996	CHANG ET AL.	
	AJ	US-5,659,952	08-26-1997	KOVAC ET AL.	
	AK	US-5,706,174	01-06-1998	DISTEFANO ET AL.	
	AL	US-5,766,987	06-16-1998	MITCHELL ET AL.	
	AM	US-5,776,796-A1	07-07-1998	DISTEFANO ET AL.	
	AN	US-5,798,286	08-25-1998	FARACI ET AL.	
$\neg \vdash$	AO	US-5,801,446	09-01-1998	DISTEFANO ET AL.	
	AP	US-5,834,339	11-10-1998	DISTEFANO ET AL.	
	AQ	US-5,843,251	12/1998	TSUKAGOSHI ET AL.	-
	AR	US-5,861,678	01/1999	SCHROCK	
1	AS	US-5,885,849	03/1999	DISTEFANO ET AL.	
	AT	US-5,915,752	02-03-1994	DISTEFANO ET AL.	
1	AU	US-5,989,936-B1	11/1999	SMITH ET AL.	
1/	AV	US-6,189,208	02/2001	ESTES ET AL.	
1/2	AW	US-6,324,754	12/2001	DISTEFANO ET AL.	
N	ΑX	US-6,460,245	10/2002	DISTEFANO	

FOREIGN PATENT DOCUMENTS							
Examiner	Cite	Foreign Patent Document	Publication	Name of Patentee or	Pages, Columns, Lines,		
Initials*	No.1	Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)	Date MM-DD-YYYY	Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	™	
						Г	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 'Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspip.gog/ or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the sarial number of the patent document. ⁶ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁸ Applicant is to place a check mark here if English language Translation is attached.

Examiner Signature	Date Considered	7/05
	,	,

PTO/SB/08a/b (08-03)
Approved for use through 07/31/2006. OMB 0551-0331
U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Sut	ostitute for form 1449A/B/PT	0		Complete If Known		
				Application Number	Not Yet Assigned	
11	NFORMATION	I DI	SCLOSURE	Filing Date	Concurrently Herewith	
S	TATEMENT E	3Y /	APPLICANT	First Named Inventor	Masud Beroz	
				Art Unit	3729	
	(Use as many sh	eets as	necessary)	Examiner Name	M. Trinh	
Sheet	2	of	2	Attorney Docket Number	TESSERA 3.0-205 A DIV	

NON PATENT LITERATURE DOCUMENTS					
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²		
T,	CA	Multi-Chip Module Technologies and Alternatives: The Basics (Doame and Franzon, eds., 1993, pp. 450-476).			
11.	СВ	RAMOS, RICHARD, Flux Free Process for Placement and Attach of Solder Balls to Wafers, Flip Chips and all BGA Packages.			
	CC	SOLBERG, Vern, Design Guidelines for Surface Mount and Fine Pitch Technology, 2d ed., Electronic Packaging and Interconnection Series.			

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

448070_1.DOC

<u> </u>	
Examiner ///	Date 2/40/0 =
Signature	Considered 2/0/0/
900	

[‡]Applicant's unique citation designation number (optional). ²Applicant is to place a check mark here if English language Translation is attached.